TOSHIBA Field Effect Transistor Silicon P-Channel MOS Type (U-MOS IV)

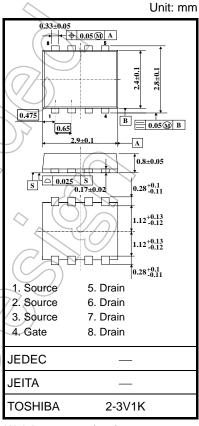
TPCP8102

Notebook PC Applications Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON-resistance: RDS (ON) = $13.5 \text{ m}\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 24 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -20 \text{ V)}$
- Enhancement model: V_{th} = -0.45 to -1.2 V (V_{DS} = -10 V, I_D = -200 μA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristic			Symbol	Rating	Unit
Drain-source voltage			V_{DSS}	-20	\\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\
Drain-gate voltage (R _{GS} = 20 kΩ)			V_{DGR}	-20	V
Gate-source voltage			V _{GSS}	± 12	V
Drain current	DC	(Note 1)	I _D	-7.2	۸
Diain current	Pulse	(Note 1)	IDP	-28.8	
Drain power dissipation (t = 5 s) (Note 2a)			PD	1.68	W
Drain power dissipation (t = 5 s) (Note 2b)			PD	0.84	w
Single-pulse avalanche energy (Note 3)			((E _{AS}))	33.7	μJ
Avalanche current			IAR	-7.2	A
Repetitive avalanche energy (Note 4)) BAR	0.168	mJ
Channel temperature			T _{ch}	150	°C
Storage temperature range			7 T _{stg}	-55~150	°C



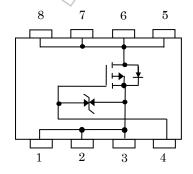
Weight: 0.017 g (typ.)

Note: For Notes 1 to 5, refer to the next page.

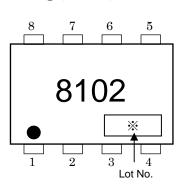
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

Circuit Configuration



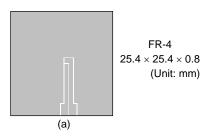
Marking (Note 5)

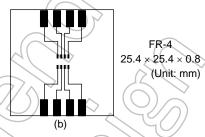


Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	R _{th (ch-a)}	74.4	°C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	R _{th (ch-a)}	148.8	°C/W

- Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.
- Note 2: (a) Device mounted on a glass-epoxy board (a)
- (b) Device mounted on a glass-epoxy board (b)





- Note 3: $V_{DD} = -16 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 0.5 mH, $R_{G} = 25 \Omega$, $I_{AR} = -7.2 \text{ A}$
- Note 4: Repetitive rating: pulse width limited by maximum channel temperature.
- Note 5: on the lower left of the marking indicates Pin 1.
 - * Weekly code (three digits):



(01 for the first week of the year, continuing up to 52 or 53)

Year of manufacture

(The last digit of the calendar year)

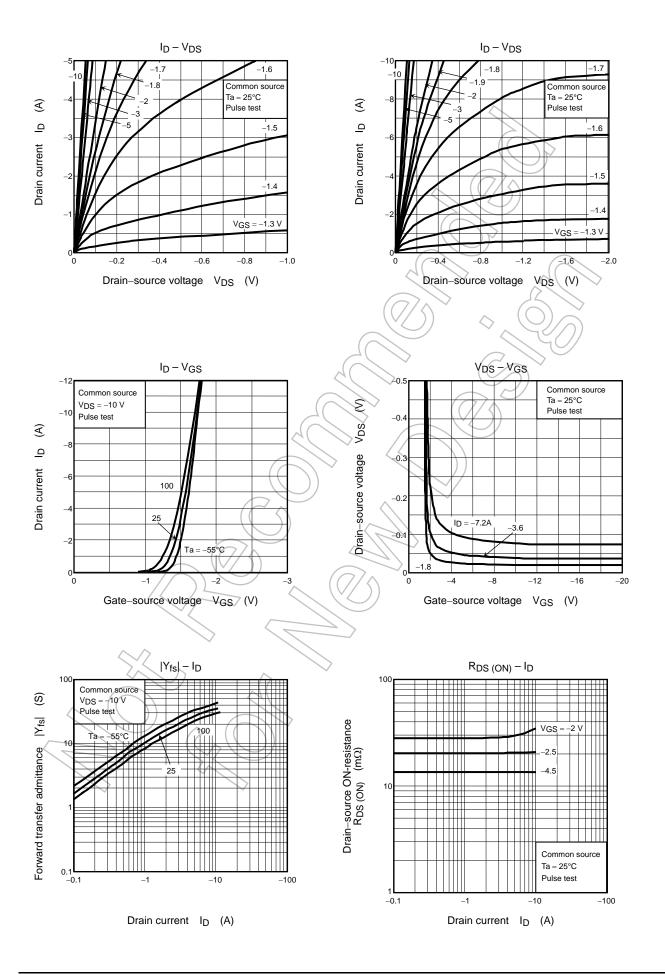


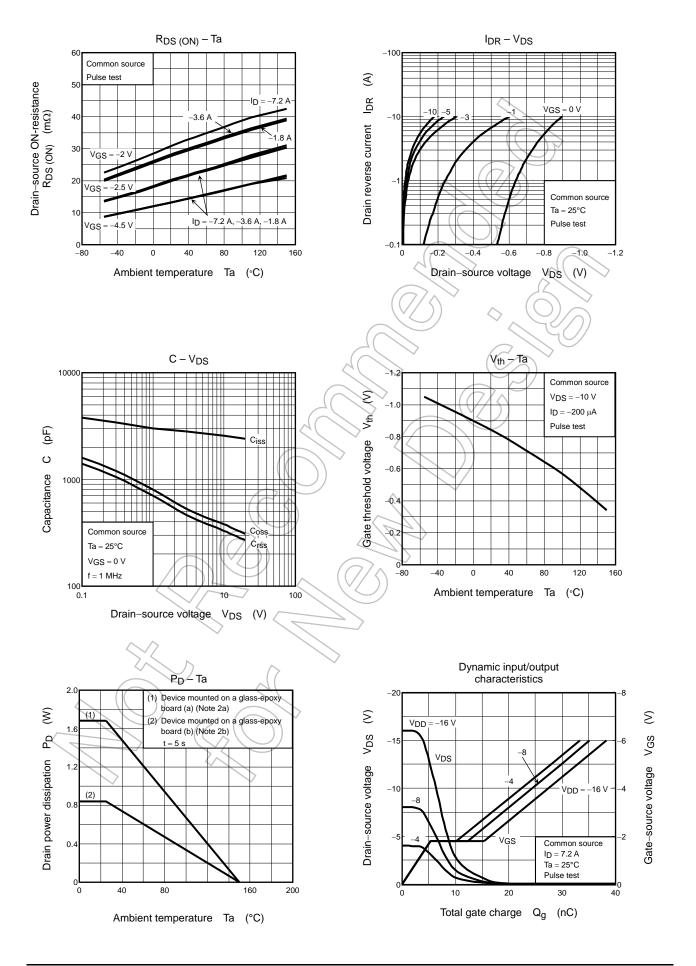
Electrical Characteristics (Ta = 25°C)

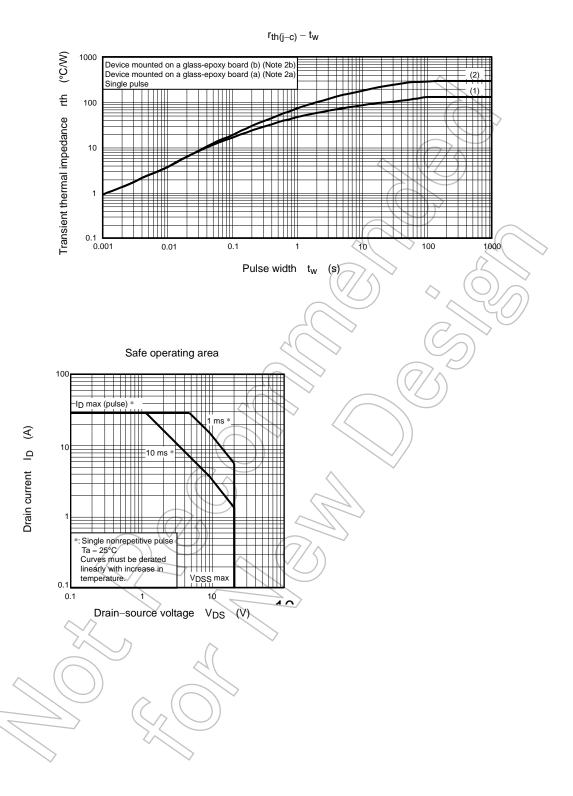
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	— ±10		μА	
Drain cutoff curre	ent	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$		10		μΑ
Drain-source breakdown voltage		V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-20	_		V
		V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 12 \text{ V}$	-8	_		V
Gate threshold vo	oltage	V _{th}	$V_{DS} = -10 \text{ V}, I_D = -200 \mu\text{A}$	-0.45))	-1.2	V
Drain-source ON-resistance			V _{GS} = -2.0 V, I _D = -1.8 A) _K	29	80	mΩ
		R _{DS} (ON)	V _{GS} = -2.5 V, I _D = -3.6 A	\rightarrow	20	30	
			V _{GS} = -4.5 V, I _D = -3.6 A)	13.5	18	
Forward transfer admittance		Y _{fs}	V _{DS} = -10 V, I _D = -3.6 A	12	24	_	S
Input capacitance		C _{iss}		_	2560	_	
Reverse transfer	capacitance	C _{rss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_ /	330	\searrow	pF
Output capacitance		C _{oss}		-6	380	> —	
Switching time	Rise time	t _r	V _{GS} 0 V 1 I _D = -3.6 A	7	5) —	
	Turn-on time	t _{on}	VGS VOUT		14	_	
	Fall time	t _f	4 m m g		42	_	ns
	Turn-off time	t _{off}	V _{DD} ≃ -10 V Duty ≦ 1%, t _w ≠ 10 μs	_	142		
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -16 \text{ V}, V_{GS} = -5 \text{ V},$	_	33	_	
Gate-source charge 1		Q _{gs1}	$I_D = -7.2 \text{ A}$	_	5.4	_	nC
Gate-drain ("Miller") charge		Q _{gd}		_	10	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Charac	teristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	\ I _{DRP}	-	_	_	-28.8	Α
Forward voltage	(diode)	V _{DSF}	I _{DR} = -3.6 A, V _{GS} = 0 V	_	_	1.2	V







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